



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



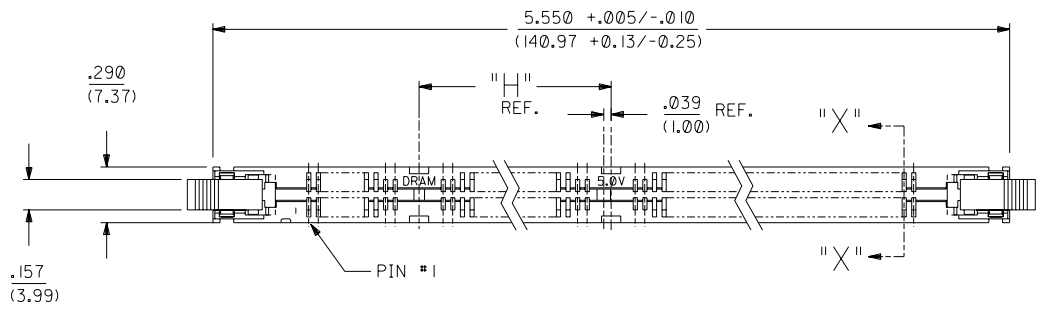
Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



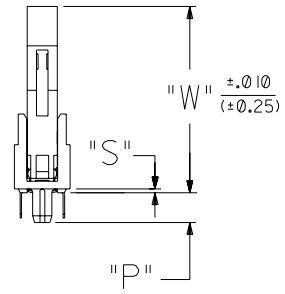


- NOTES:
- CARD SLOT ACCEPTS $.050 \pm .004$ (1.27 ± 0.10) MODULE THICKNESS. (MEASURED OVER P.C. PADS).
 - ALL PEGS ARE INTERFERENCE FITS TO PCB UNLESS NOTED ON THE DWG.
 - REFER TO PRODUCT SPEC PS-71243-9999 FOR PERFORMANCE SPECIFICATIONS.
 - PRODUCT IS PACKAGED IN TRAYS.
 - RECOMMENDED MODULE LAYOUT SHALL BE PER JEDEC MO-161.
 - RECOMMENDED PLATING ON MODULE PADS: 30 MICROINCH/(0.76 MICROMETER) MINIMUM HARD GOLD (Au) OVER 79 MICROINCH/(2.0 MICROMETER) MINIMUM NICKEL (Ni).
 - SEE CHART FOR HOLE SIZE AND PRESENCE AND PLATING OPTION.
 - PRODUCT WILL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.

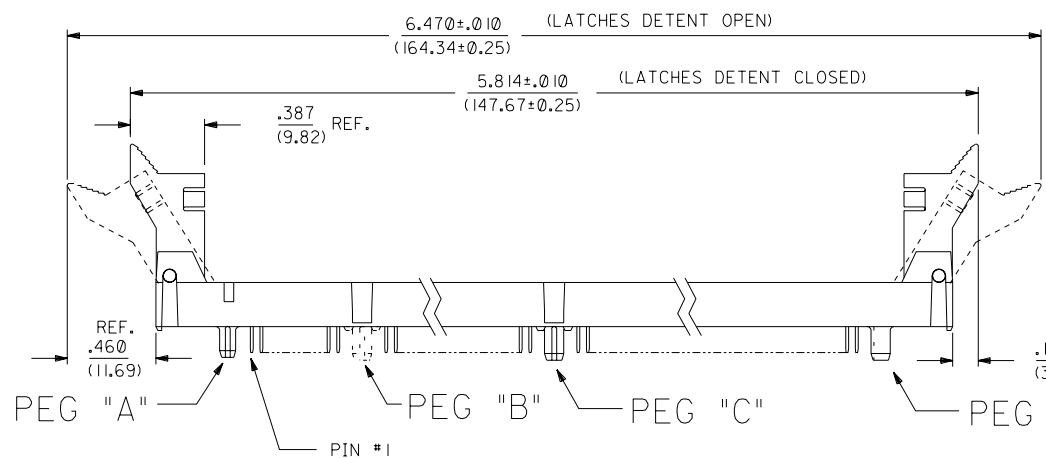
MATERIALS:
 HOUSING - GLASS FILLED LIQUID CRYSTAL POLYMER (LCP), UL 94V-0, COLOR: BLACK.
 TERMINAL - PHOSPHOR BRONZE
 LATCHES - GLASS FILLED HIGH TEMPERATURE NYLON, UL 94V-0, COLOR: IVORY.

PLATING:
 CONTACT AREA: OPTION A: GOLD (Au) FLASH; THICKNESS=2-10 MICROINCH/(0.05-0.25 (0.05-0.25 MICROMETER), OVER PALLADIUM-NICKEL (Pd-Ni); THICKNESS=30 MICROINCH/(0.76 MICROMETER) MINIMUM.
 OPTION B: GOLD (Au) FLASH; THICKNESS=2-10 MICROINCH/(0.05-0.25 MICROMETER), OVER PALLADIUM-NICKEL (Pd-Ni); THICKNESS=20 MICROINCH/(0.51 MICROMETER) MINIMUM.

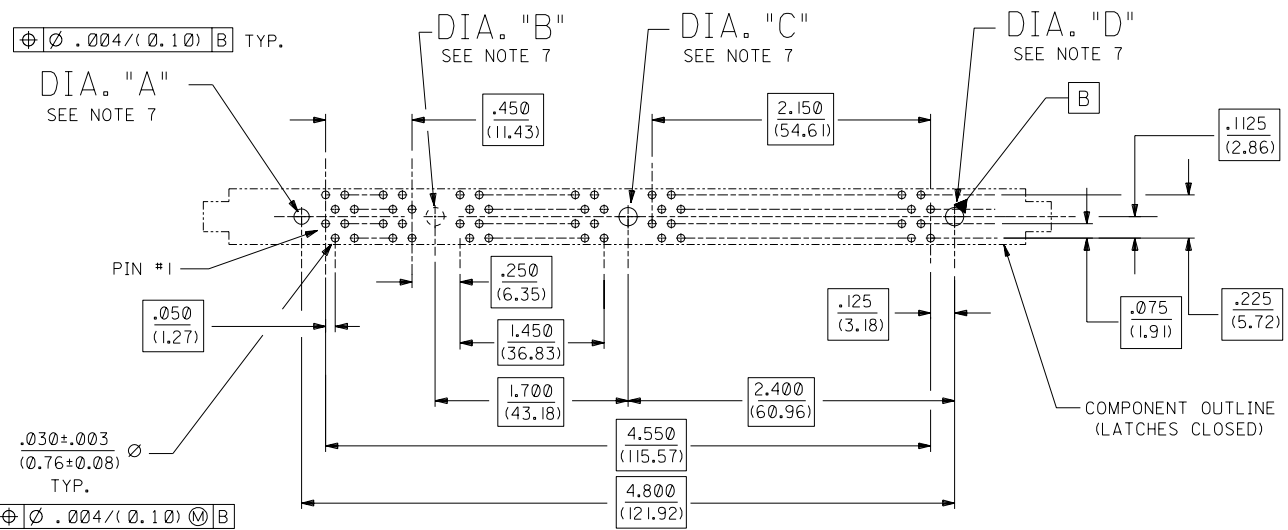
SOLDER TAILS: TIN (Sn); THICKNESS=150 MICROINCH/(3.81 MICROMETER) MINIMUM.
 UNDERPLATE: NICKEL (Ni) OVER ENTIRE CONTACT.



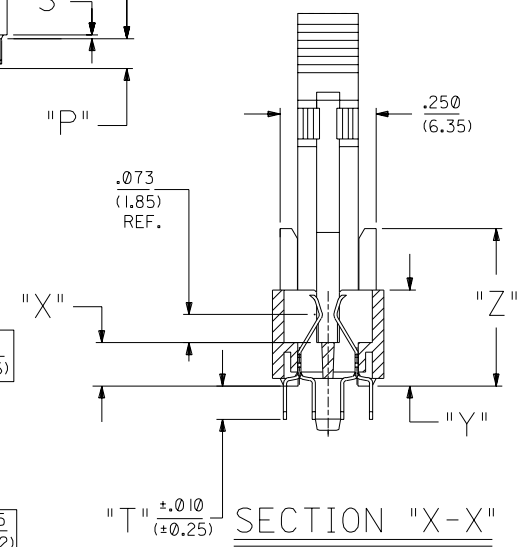
NOTE FOR LEAD FREE CONVERSION:
 THE PRIMARY SHIPPING CARTON WILL BE LABELED "COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC". CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.



71251-0004 SHOWN



RECOMMENDED
 P.C. BOARD HOLE PATTERN
 (CONNECTOR SIDE)



SECTION "X-X"

SCALE 4:1

H1	ADD LEAD FREE NOTE ECR# UC2004-1732 DMORGAN 04/03/09
H	RELEASE -0027 ECR# UD2000-1151 DMORGAN 00/05/19
H	RELEASE -0027 ECR# UD2000-1151 DMORGAN 00/05/19
G	CHG Sn-Pb THICKNESS ECR# UD1999-0454 DMORGAN 99/08/09
F3	REVISED PER ECR# U80435 97-8-8 LAURX
F2	REVISED PER ECR# U71162 97-4-15 LAURX
F1	REVISED PER ECR# U70361 96-10-9 LAURX
F	REVISED PER ECR# U61133 96-9-25 LAURX
E1	REVISED PER ECR# U60836 1-19-96 JCL
E	REVISED PER ECR# U60682 12-7-95 JCL
D2	REVISED PER ECR# U60452 10-10-95 JCL
D1	REVISED PER ECR# U60361 9-18-95 JCL
D	REVISED PER ECR# U51288 8-4-95 JCL

DIMENSIONS SHOWN (METRIC) INCH		UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
3 PLACE ± .005	INCH	---	METRIC
2 PLACE ± --- ± 0.13	---	---	---
1 PLACE --- ± 0.25	---	---	---
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY: DCB	CHK'D BY: DCB	FILE NAME: S7125101.DGN	SCALE: 2:1
TITLE: .050/(1.27) PITCH MULTI-KEY 168 CKT DIMM RAM ASSY 17.8mm LATCH SALES DWG		MOLX INCORPORATED	
PART NO. SDA-71251-0***		SHEET NO. 1 OF 3	
DATE: 10/10/94		U.S.A.	
MFG. SH. REV. LTR. REVISIONS		REVISE ONLY ON CAD SYSTEM	
3	H		
2	F3		
1	H1		

